

# SAMXON BRAND ALUMINUM ELECTROLYTIC CAPACITORS PRODUCT SPECIFICATION 規格書

**CUSTOMER :** 

(**客戶**):九昇昌

DATE :

(日期):2020-10-29

CATEGORY (品名)	:	ALUMINUM ELECTROLYTIC CAPACITORS
DESCRIPTION (型号)	:	HP $400V390\mu F(\varphi 30x35)$
VERSION (版本)	:	01
Customer P/N	:	
SUPPLIER	:	

SUPPL	IER	CUSTOMER				
PREPARED (拟定)	CHECKED (审核)	APPROVAL (批准)	SIGNATURE (签名)			
邓文文	付婷婷					

#### ELECTROLYTIC CAPACITOR SPECIFICATION HP SERIES

		SPECIFICAT HP SERIE			ALTERNA	ATION HIST ECORDS	ORY
Rev.	Date	Mark	Page	Contents	Purpose	Drafter	Approver
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Name		Specification Sheet – HP				
Version	01		Page	1		
STANDARD MANUAL						

MAN YUE ELECTRONICS	ELECTROLYTIC CAPACITOR	SAMXON
COMPANY LIMITED	SPECIFICATION HP SERIES	

#### Table 1 Product Dimensions and Characteristics

Z-TYPE

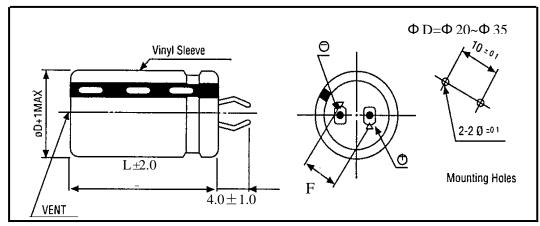


Table 1

Part No.     (Vdc)     ( $\mu$ F)     tolerance     range(°C)     ( $\mu$ C)     ( $\mu$ C)     ( $\mu$ F)     tolerance     range(°C)     ( $\mu$ C)     ( $\mu$ C)	No	SAMXON	WV	Cap.	Cap	Temp.	tan <b>ð</b> (120Hz,	Leakage Current	Max Ripple Current at 105°C 120Hz	Load lifetime	Dimen (mi		Sleeve
1       EHP397M2GP35SZ**P       400       390       -20%~+20%       -25~105       0.20       1185       1.3       2000       30X35       10±1.0       PET		Part No.	(Vdc)	(µF)	tolerance	range(°C)					D×L	F	
	1	EHP397M2GP35SZ**P	400	390	-20%~+20%	-25~105	0.20	1185	1.3	2000	30X35	$10\pm1.0$	PET

Issued-date: 2020-10-29		Specification Sheet – HP				
Version 01 Page 2						
STANDARD MANUAL						

<ul> <li>Part Number System</li> <li>Part Number System</li> <li>Construction</li> <li>Construction</li> <li>Characteristics</li> <li>Characteristics</li> <li>Capacitance (Tolerance)</li> <li>Leakage current</li> <li>Leakage current</li> <li>List and</li> <li>Terminal strength</li> <li>Terminal strength</li> <li>Temperature characteristics</li> <li>Tend life test</li> <li>Shelf life test</li> <li>Substance to solder heat</li> <li>State and the state st</li></ul>	Part Number System       4         Construction       5         Characteristics       6~13         ated voltage & Surge voltage       6~13         ated voltage & Surge voltage       6         characteristics       6         ated voltage & Surge voltage       6         vibration       6         Solderability test       6         Resistance to solder heat       6         Charge of temperature       6         Damp heat test       6         atest       6         atest       6         atest	C O N T E N T S	Sheet
<ul> <li>3. Construction</li> <li>4. Characteristics</li> <li>4. Characteristics</li> <li>4. Rated voltage &amp; Surge voltage</li> <li>4.2 Capacitance (Tolerance)</li> <li>4.3 Leakage current</li> <li>4.4 tanõ</li> <li>4.5 Terminal strength</li> <li>4.6 Temperature characteristics</li> <li>4.7 Load life test</li> <li>4.8 Shelf life test</li> <li>4.9 Surge test</li> <li>4.10 Vibration</li> <li>4.11 Solderability test</li> <li>4.12 Resistance to solder heat</li> <li>4.13 Change of temperature</li> <li>4.14 Damp heat test</li> <li>4.15 Vent test</li> <li>4.16 Maximum permissible (ripple current)</li> <li>5. List of "Environment-related Substances to be Controlled ('Controlled Substances')"</li> </ul>	Construction       5         Characteristics       6~13         ated voltage & Surge voltage       6~13         capacitance (Tolerance)       eeakage current         anð       6         verminal strength       emperature characteristics         oad life test       6         helf life test       6         urge test       Vibration         Solderability test       6         Resistance to solder heat       6         Change of temperature       6         Damp heat test       6         test       6         12       12	1. Application	4
<ul> <li>4. Characteristics 6~13</li> <li>4.1 Rated voltage &amp; Surge voltage</li> <li>4.2 Capacitance (Tolerance)</li> <li>4.3 Leakage current</li> <li>4.4 tanδ</li> <li>4.5 Terminal strength</li> <li>4.6 Temperature characteristics</li> <li>4.7 Load life test</li> <li>4.8 Shelf life test</li> <li>4.8 Shelf life test</li> <li>4.9 Surge test</li> <li>4.10 Vibration</li> <li>4.11 Solderability test</li> <li>4.12 Resistance to solder heat</li> <li>4.13 Change of temperature</li> <li>4.14 Damp heat test</li> <li>4.15 Vent test</li> <li>4.16 Maximum permissible (ripple current)</li> <li>5. List of "Environment-related Substances to be Controlled ('Controlled Substances')"</li> </ul>	Characteristics       6~13         ated voltage & Surge voltage       6         capacitance (Tolerance)       eakage current         unδ       6         'erminal strength       emperature characteristics         coad life test       6         helf life test       6         urge test       Vibration         Solderability test       Resistance to solder heat         Change of temperature       0         Damp heat test       12	2. Part Number System	4
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5. List of "Environment-related Substances to be Controlled ('Controlled 12 Substances')"	t of "Environment-related Substances to be Controlled ('Controlled 12 ubstances')"	4.15 Vent test	
Substances')"	ubstances')"		
Attachment: Application Guidelines 13~1	ttachment: Application Guidelines 13~17		12
		Attachment: Application Guidelines	13~17
		Attachment. Application Guidennes	15 17

Version 01 Page 3	
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#### ELECTROLYTIC CAPACITOR **SPECIFICATION** HP SERIES

SAMXON

#### Application 1.

This specification applies to polar Aluminum electrolytic capacitor (foil type) used in electronic equipment. Designed capacitor's quality meets IEC60384. Part Number System

#### 2.

Series Series ESM EKF EGS EGS EKM EKG		CITAN Code 104	Tolerance (%)		VOLTAGE	-	D 1 1 CASE SIZE			SA	SLEEVE
Series ESM EKF ESS EKS EGS EKM	Cap(MFD) 0.1 0.22	Code 104	Tolerance (%)		VOLTAGE	-	CASE SIZE	TYP			SLEEVE
ESM EKF ESS EKS EGS EKM	0.1	104		Code					F	SAMXON PRODUCT LINE N	
EKF ESS EKS EGS EKM	0.22				Voltage (W.V.)		Case Size	Feature (	Code	SAMXON Product	_ine
EGS EKM			±5	J	2 2.5	0D 0E	Diameter(e) Code 3 B 3.5 1	Radial bulk	RR	For internal use only (The product lines	<pre>/</pre>
	0.33	224	±10	к	4 6.3	0G 0J	4 C 5 D 6.3 E	Ammo Tap	ing	we have H,A,B,C,D E,M or 0,1,2,3,4,5,9	
EOM		334	±15	L	8 10	0K 1A	8 F 10 G 12.5 I	2.0mm Pitch	Π		
EZM EZS EGF	0.47	474	±15		12.5 16	1B 1C	13 J 13.5 V	2.5mm Pitch	τu		
ESF EGT EGK	1	105	±20	м	20 25	1D 1E	14 4 14.5 A 16 K	3.5mm Pitch	тν	Sleeve Material	Code
EGE	2.2	225	±30	N	30 32	1I 13	16.5 7 18 L 18.5 8	5.0mm Pitch	тс	PET	P
EGC ERS ERF	3.3	335	-40 0	w	35 40	1V 1G	20 M 22 N	Lead Cut & F	=orm		
ERL	4.7	475	-20	A	40 42 50	1M 1H	25 O 30 P 34 W	СВ-Туре	СВ		
ERT ERE ERD	10	106	-20		57	1L		СЕ-Туре	CE		
ERH EBD ERA	22	226	+10	с	63 71	1J 1S	42 4 45 6 51 S	HE-Type	HE		
ERB	33	336	-20 +40	×	75 80	1T 1K	63.5 T 76 U 80 8	KD-Type	КD		
EFA ENP ENH	47	476	-20 +50	s	85 90	1R 19	90 X 100 Z Len.(mm) Code	FD-Type	FD		
ERW ERY ELP	100	107	-10 0	в	100 120	2A 2O	4.5 45 5 05	EH-Type	EH		
EAP EQP	220	227	-10 +20	v	125 150	2B 2Z	5.4 54 7 07 7.7 77	PCB Term	ial		
EDP ETP EHP	330	337	-10	Q	160 180	2C 2P	10.2 T2 11 11		sw		
EUP EKP	470	477	+30	т	200 215	2D 22	11.5 1A 12 12 12.5 1B 13 13	Snap-in	sx		
EEP EFP ESP	2200	228	+50		220	2N 23	13.5 1C		sz		
EVP EGP EWR	22000	229	+10	E	230 250	2E	25 25 29.5 2J	Lug	SG		
EWU EWT	33000	339	+15	F	275 300	2T 2I	30 30 31.5 3A 35 35 35.5 3E		05	L	
EWX EWF EWS	47000	479	+20	G	310 315	2R 2F	35.5 3E 50 50 80 80		06		
EWH EWL	100000	10T	0 +20	R	330 350	2U 2V	100 1L 105 1K		т5		
VSS VNS			0 +30	0	360 375	2X 2Q	110 1M 120 1N 130 1P	Screw	т6		
VKS VKM	150000	15T	0 +50	I.	385 400	2Y 2G	140 1Q 150 1R		D5		
VNH VZS	220000	22T	+5 +15	z	420	2M 2W	160 1S		D6		
	330000	33T	+5 +20	D	500	2H 25	165 1F 170 1T 180 1U 190 1V				
ŀ	1000000	10M	+10 +50	Y	600	26	190 1V 200 2L 215 2A 210 2M 220 2N 240 2Q 250 2R				
-	1500000	15M	+10 +30	н	630	2J	210 2M 220 2N 240 2Q				
ŀ	2200000	22M			1		250 2R 260 2S 270 2T				
	3300000	33M					270 [21]				

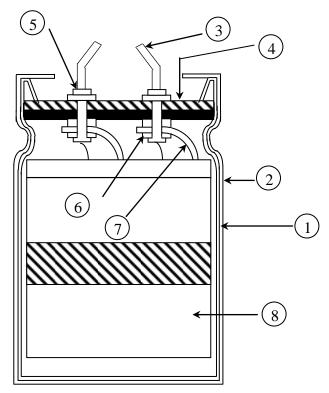
Version 01 Page 4
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#### ELECTROLYTIC CAPACITOR SPECIFICATION HP SERIES

SAMXON

#### 3. Construction

Single ended type to be produced to fix the terminals to anode and cathode foil, and wind together with paper, and then wound element to be impregnated with electrolyte will be enclosed in an aluminum case. Finally sealed up tightly with end seal rubber, then finished by putting on the vinyl sleeve.



No	Component	Material
1	Case	Aluminum case
2	Sleeve	PET
3	Terminal	Solder coated copper clad steel
4	Seal	Rubber-laminated Bakelite
5	Rivet	Aluminum
6	Washer	Aluminum
7	Tab	Aluminum
8	Element	Aluminum foil & Electrolyte paper

Version 01 Page 5
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SAMXON

#### 4. Characteristics

Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature	:15°C to 35°C
Relative humidity	: 45% to 85%
Air Pressure	: 86kPa to 106kPa

If there is any doubt about the results, measurement shall be made within the following conditions:Ambient temperature:  $20^{\circ}C \pm 2^{\circ}C$ Relative humidity: 60% to 70%Air Pressure: 86kPa to 106kPa

#### Operating temperature range

The ambient temperature range at which the capacitor can be operated continuously at rated voltage See table 1 temperature range.

As to the detailed information, please refer to table 2

Version	01	Page	6

#### ELECTROLYTIC CAPACITOR SPECIFICATION HP SERIES

Table 2													
	ITEM					PER	FORM	IANCI	Ξ				
					-								
		WV (	V.DC)	10	16	25	35	50	63	80	0	100	160
	Rated voltage			10	•				-	10			• • •
	(WV)	SV (	V.DC)	13	20	32	44	63	79	10	00	125	200
4.1		WIN (	(V .DC)	180	200	220	250	315	350	400	420	450	500
		vv v (	(V.DC)	160	200	220	230	515	330	400	420	430	500
	Surge voltage	SV (	V.DC)	225	250	270	300	365	400	450	470	500	550
	(SV)												
		<con< td=""><td>ndition&gt;</td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></con<>	ndition>										
	Nominal	Meas	suring Fre	equenc	y :1	20Hz	±12Hz	5					
4.2	capacitance (Tolerance)		suring Vo	-	•	Not mo	re than	0.5Vr	ms				
	(Toleralice)	Meas	suring Te	mperat	ure :2	$20\pm2^\circ$	С						
			teria> S	hall be	within	the sp	ecified	capaci	tance t	oleran	ce		
			ndition>										
4.3	Leakage		necting the						stor (]	$k\Omega \pm$	10Ω)	in seri	es for :
	current		tes, and the				e Curr	ent.					
		<criteria> Refer to table 1 <condition></condition></criteria>											
4.4	tanδ	See 4.2, Norm Capacitance, for measuring frequency, voltage and temperature.											
7.7	tano	<criteria> Refer to table 1</criteria>											
		<(	Condition	>									
					5N (2.5	5kgf) sl	hall be	applie	d to the	e lead v	wire te	rminal	in the
4 5	Terminal	A static load of 25N (2.5kgf) shall be applied to the lead wire terminal in the axial direction away from the capacitor body for 30s											
4.5	strength		<criteria></criteria>										
		There shall be no intermittent contacts, open or short circuit and there shall be no mechanical damage such as terminal damage.											
					ge such	as terr	ninai d	amage	•				
		<(	Condition STEP		ng Tem	norotu	$r_{\alpha}(^{\circ}C)$	Time	<b>a</b>				
		_	1	Tesu	20	-				ch the	rmal e	quilibri	um
		-	2									quilibri	
		_	3			$\frac{25)\pm 3}{\pm 2}$						quilibri	
		_	4			$\frac{\pm 2}{5\pm 2}$						quilibri	
		-	5			$\pm 2$						quilibri	
			Criteria>1	iomΣ a1			41a a 12m					quinon	um
	Temperature		e leakage							imas o	f ite en	acified	voluo
4.6	characteristics		In step :								n ns sp	ecmeu	value.
	characteristics	а.	The lea								value		
		b.	At-40°C	-					-			e of the	
			followin		-								
		Γ	Working			10~2	5	35	50	63~	·100	160-	-500
				C/Z+20		6		6	4		3	8	3
			Z-40°	C/Z+20	)°C	15		15	15	1	5		
		Ċ	Capacitand	ce, tand	5, and	imped	ance sł	all be	measui	ed at 1	20Hz		
						_							
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	Version		01								Pag	e 7	
	v 0151011		01								1 ag	~ /	

		temperature of $105 \ \C$ $\pm$ for Table 1 (The sum	4No.4.13 methods, The capac 2 with DC bias voltage plus of DC and ripple peak voltag Then the product should b spheric conditions.	the rated ripple current ge shall not exceed the
4.7	Load life test	The result should meet t < <b>Criteria&gt;</b> The characteristic shall n Leakage current Capacitance Change tanδ	he following table: neet the following requirement Value in 4.3 shall be satisfied Within $\pm 20\%$ of initial value Not more than 200% of the	ed lue . specified value.
		Appearance	There shall be no leakage of	f electrolyte
4.8	Shelf life test	$\pm 2$ °C for 1000+48/0 hours Following this period the c be allowed to stabilized at Next they shall be connect rated voltage applied for 30 and then, tested the charac <b><criteria></criteria></b> The characteristic shall m Leakage current Capacitance Change tanδ Appearance Remark: If the capacito	apacitors shall be removed fro room temperature for 4~8 hor ed to a series limiting resistor Omin. After which the capacit	ts. ed lue . specified value. f electrolyte r, the leakage current
4.9	Surge test	resistor. The capacitor shall be sub $30 \pm 5s$ , followed discharg The test temperature shall $C_R$ :Nominal Capacitance ( <b><criteria></criteria></b> Leakage current Capacitance Change tan $\delta$ Appearance Attention:	be 15~35°C. (µ F) Not more than the specif Within ±15% of initial Not more than the specif There shall be no leakage oltage at abnormal situation, a	consisting of charge of fied value. value. fied value. e of electrolyte
	Version	01		Page 8
	v CI 51011	01		rage 0

ELECTROLYTIC CAPACITOR SPECIFICATION HP SERIES



4.10 Vibration test	<b>Condition&gt;</b> The following conditions shall be applied for 2 hours in each perpendicular directions. Vibration frequency range : 10Hz ~ 55Hz Peak to peak amplitude : 1.5mm Sweep rate : 10Hz ~ 55Hz ~ 10Hz in about 1 <b>Criteria&gt;</b> After the test, the following items shall be tested: Appearance No mechanical damage in terminal. N electrolyte or swelling of the case. Th be legible. Inner No intermittent contact, open or short No damage of tab terminals or electrolyte or subscription. Mounting method: The capacitor must be fixed in place with the soldered of the test of the test of the case. <b>Construction</b> After the capacitor must be fixed in place with the soldered of the test of the test of the case. <b>Construction Construction Constru</b>	o leakage of e markings shall circuit. des.
4.11 Solderabilit y test	<condition>         The capacitor shall be tested under the following conditions:         Soldering temperature       : 245±3°C         Dipping depth       : 2mm         Dipping speed       : 25±2.5mm/s         Dipping time       : 3±0.5s         <criteria>       A minimum of 95% of th immersed</criteria></condition>	e surface being
4.12 Resistance to solder heat test	<condition>Terminals of the capacitor shall be immersed into solder bath<math>260 \pm 5^{\circ} C \text{ for } 10 \pm 1 \text{ seconds or } 400 \pm 10^{\circ} C \text{ for } 3^{+1}_{-0} \text{ seconds to }</math>body of capacitor .Then the capacitor shall be left under the normal temperaturefor 1~2 hours before measurement.<criteria>Leakage currentNot more than the specified vCapacitance ChangeWithin <math>\pm 10\%</math> of initial valuetan<math>\delta</math>Not more than the specified vAppearanceThere shall be no leakage of e</criteria></condition>	1.5~2.0mm from the and normal humidity alue. e . alue.
Version		

#### ELECTROLYTIC CAPACITOR SPECIFICATION HP SERIES

		<condition></condition>					
		Temperature Cycle:					
				pacitor shall be placed in an			
		oven, the condition a					
			emperature	Time			
		(1)+20°C		$\leq 3$ Minutes			
4.13	Change of temperature	(2)Rated low temper		$30\pm 2$ Minutes			
	test	(3)Rated high temper	rature (+105 $^{\circ}$ C)	$30\pm 2$ Minutes			
		(1) to (3)=1 cycle, to	tal 5 cycle				
		<criteria></criteria>					
		The characteristic shall					
		Leakage current	Not more than the	•			
		tanδ	Not more than the	specified value.			
		Appearance	There shall be no l	eakage of electrolyte			
		<condition></condition>					
		Humidity Test:					
			1-4No 4 12methods car	pacitor shall			
		According to IEC60384-4No.4.12methods, capacitor shall be exposed for 500±8 hours in an atmosphere of 90~95% R H .at					
	5	$40\pm2^{\circ}$ , the characteristic change shall meet the following requirement.					
4.14	Damp		istic change shall meet	the following requirement.			
	heat	<criteria></criteria>		· C· 1 1			
	test	Leakage current	Not more than the spe				
		Capacitance Change	Within $\pm 20\%$ of ini	tial value .			
		tanδ	Not more than 120%	of the specified value.			
		Appearance	There shall be no leal	kage of electrolyte.			
		<condition></condition>					
		The following test only	apply to those product	s with vent.			
		D.C. test					
				reversed to a DC power source			
			from Table 2 is applie	ed.			
	Vent	<table 3=""></table>					
4.15	test	Diameter (mm) D	C Current (A)				
		22.4 or less	1				
		Over 22.4	10				
		<criteria></criteria>					
		The vent shall operation	te with no dangerous	conditions such as flames			
		dispersion of pieces of	the capacitor and/or ca	se.			

Version	01		Page	10
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#### ELECTROLYTIC CAPACITOR SPECIFICATION HP SERIES



4.16 Maximum permissible (ripple current) $Frequency Multipliers:$ Coefficient (Hz) 000000000000000000000000000000000000			<condition> The maximum permissible at 120Hz and can be applie Table-1 The combined value of D.C rated voltage and shall not</condition>	ed at maxim	um operatin l the peak A	g temperat	ure
4.10         current )         10~100V         0.90         1.00         1.15         1.25           160~250V         0.80         1.00         1.25         1.47		permissible	Coefficient (Hz)	60	120	1k	10~50k
	4.16		10~100V	0.90	1.00	1.15	1.25
315~500V 0.80 1.00 1.30 1.47							
			315~500V	0.80	1.00	1.30	1.47

Version	01	Page	11

#### ELECTROLYTIC CAPACITOR SPECIFICATION HP SERIES

# SAMXON

# 5. It refers to the latest document of "Environment-related Substances standard"(WI-HSPM-QA-072).

	Substances
	Cadmium and cadmium compounds
Heavy metals	Lead and lead compounds
Heavy metals	Mercury and mercury compounds
	Hexavalent chromium compounds
	Polychlorinated biphenyls (PCB)
Chloinated	Polychlorinated naphthalenes (PCN)
organic	Polychlorinated terphenyls (PCT)
compounds	Short-chain chlorinated paraffins(SCCP)
	Other chlorinated organic compounds
	Polybrominated biphenyls (PBB)
Brominated organic compounds	Polybrominated diphenylethers(PBDE) (including
	decabromodiphenyl ether[DecaBDE])
compounds	Other brominated organic compounds
Tributyltin comp	pounds(TBT)
Triphenyltin con	npounds(TPT)
Asbestos	
Specific azo con	npounds
Formaldehyde	
Polyvinyl chlori	de (PVC) and PVC blevds
Beryllium oxide	
Beryllium copp	ber der der der der der der der der der d
Specific phthalat	tes (DEHP,DBP,BBP,DINP,DIDP,DNOP,DNHP)
Hydrofluorocarb	oon (HFC), Perfluorocarbon (PFC)
Perfluorooctane	sulfonates (PFOS)
Specific Benzotr	iazole

	Version	01		Page	12
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#### Attachment: Application Guidelines 1.Circuit Design

1.1 Operating Temperature and Frequency

Electrolytic capacitor electrical parameters are normally specified at  $20^{\circ}$ C temperature and 120Hz frequency. These parameters vary with changes in temperature and frequency. Circuit designers should take these changes into consideration.

- (1) Effects of operating temperature on electrical parameters
  - a) At higher temperatures, leakage current and capacitance increase while equivalent series resistance (ESR) decreases.
  - b) At lower temperatures, leakage current and capacitance decrease while equivalent series resistance (ESR) increases.
- (2) Effects of frequency on electrical parameters
  - a) At higher frequencies capacitance and impedance decrease while  $tan\delta$  increases.
  - b) At lower frequencies, ripple current generated heat will rise due to an increase in equivalent series resistance (ESR).
- 1.2 Operating Temperature and Life Expectancy See the file: Life calculation of aluminum electrolytic capacitor
- 1.3 Common Application Conditions to Avoid

The following misapplication load conditions will cause rapid deterioration to capacitor electrical parameters. In addition, rapid heating and gas generation within the capacitor can occur causing the pressure relief vent to operate and resultant leakage of electrolyte. Under Leaking electrolyte is combustible and electrically conductive.

(1) Reverse Voltage

DC capacitors have polarity. Verify correct polarity before insertion. For circuits with changing or uncertain polarity, use DC bipolar capacitors. DC bipolar capacitors are not suitable for use in AC circuits.

#### (2) Charge / Discharge Applications Standard capacitors are not suitable for use in repeating charge / discharge applications. For charge / discharge applications consult us and advise actual conditions.

(3) Over voltage

Do not apply voltages exceeding the maximum specified rated voltage. Voltages up to the surge voltage rating are acceptable for short periods of time. Ensure that the sum of the DC voltage and the superimposed AC ripple voltage does not exceed the rated voltage.

(4) Ripple Current

Do not apply ripple currents exceeding the maximum specified value. For high ripple current applications, use a capacitor designed for high ripple currents or contact us with your requirements.

Ensure that allowable ripple currents superimposed on low DC bias voltages do not cause reverse voltage conditions.

- 1.4 Using Two or More Capacitors in Series or Parallel
- (1) Capacitors Connected in Parallel

The circuit resistance can closely approximate the series resistance of the capacitor causing an imbalance of ripple current loads within the capacitors. Careful design of wiring methods can minimize the possibility of excessive ripple currents applied to a capacitor.

(2) Capacitors Connected in Series

Normal DC leakage current differences among capacitors can cause voltage imbalances. The use of voltage divider shunt resistors with consideration to leakage current can prevent capacitor voltage imbalances.

Version 01 Page 1	3
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SAMXON

- 1.5 Capacitor Mounting Considerations
- (1) Double Sided Circuit Boards

Avoid wiring pattern runs, which pass between the mounted capacitor and the circuit board. When dipping into a solder bath, excess solder may collect under the capacitor by capillary action and short circuit the anode and cathode terminals.

(2)Circuit Board Hole Positioning

The vinyl sleeve of the capacitor can be damaged if solder passes through a lead hole for subsequently processed parts. Special care when locating hole positions in proximity to capacitors is recommended.

(3)Circuit Board Hole Spacing

The circuit board holes spacing should match the capacitor lead wire spacing within the specified tolerances.
Incorrect spacing can cause excessive lead wire stress during the insertion process. This may result in premature capacitor failure due to short or open circuit, increased leakage current, or electrolyte leakage.
(4) Clearance for Case Mounted Pressure Relief vents

Capacitors with case mounted pressure relief vents require sufficient clearance to allow for proper vent operation. The minimum clearances are dependent on capacitor diameters as proper vent operation. The minimum clearances are dependent on capacitor diameters as follows.

 $\varphi$  6.3~ $\varphi$  16mm:2mm minimum,  $\varphi$  18~ $\varphi$  35mm:3mm minimum,  $\varphi$  40mm or greater:5mm minimum.

(5) Clearance for Seal Mounted Pressure Relief Vents

A hole in the circuit board directly under the seal vent location is required to allow proper release of pressure. (6) Wiring Near the Pressure Relief Vent

Avoid locating high voltage or high current wiring or circuit board paths above the pressure relief vent. Flammable, high temperature gas exceeding 100°C may be released which could dissolve the wire insulation and ignite.

(7) Circuit Board patterns Under the Capacitor

Avoid circuit board runs under the capacitor as electrolyte leakage could cause an electrical short.

(8) Screw Terminal Capacitor Mounting

Do not orient the capacitor with the screw terminal side of the capacitor facing downwards.

Tighten the terminal and mounting bracket screws within the torque range specified in the specification.

- 1.6 Electrical Isolation of the Capacitor Completely isolate the capacitor as follows.
- (1) Between the cathode and the case (except for axially leaded B types) and between the anode terminal and other circuit paths
- (3) Between the extra mounting terminals (on T types) and the anode terminal, cathode terminal, and other circuit paths.
- 1.7 The Product characteristic should take the sample as the standard.
- 1.8 Capacitor Sleeve

The vinyl sleeve or laminate coating is intended for marking and identification purposes and is not meant to electrically insulate the capacitor.

The sleeve may split or crack if immersed into solvents such as toluene or xylene, and then exposed to high temperatures.

#### CAUTION!

Always consider safety when designing equipment and circuits. Plan for worst case failure modes such as short circuits and open circuits which could occur during use.

(1) Provide protection circuits and protection devices to allow safe failure modes.

(2) Design redundant or secondary circuits where possible to assure continued operation in case of main circuit failure.

	Version	01		Page	14
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#### 2. Capacitor Handling Techniques

- 2.1 Considerations Before Using
- (1) Capacitors have a finite life. Do not reuse or recycle capacitors from used equipment.
- (2) Transient recovery voltage may be generated in the capacitor due to dielectric absorption. If required, this voltage can be discharged with a resistor with a value of about  $1k\Omega$ .
- (3) Capacitors stored for long periods of time may exhibit an increase in leakage current. This can be corrected by gradually applying rated voltage in series with a resistor of approximately  $1k\Omega$ .
- (4) If capacitors are dropped, they can be damaged mechanically or electrically. Avoid using dropped capacitors.
- (5) Dented or crushed capacitors should not be used. The seal integrity can be compromised and loss of electrolyte / shortened life can result.

#### 2.2 Capacitor Insertion

- \* (1) Verify the correct capacitance and rated voltage of the capacitor.
- \* (2) Verify the correct polarity of the capacitor before inserting.
- \* (3) Verify the correct hole spacing before insertion (land pattern size on chip type) to avoid stress on the terminals.
  - (4) Ensure that the auto insertion equipment lead clinching operation does not stress the capacitor leads where they enter the seal of the capacitor.

For chip type capacitors, excessive mounting pressure can cause high leakage current, short circuit, or disconnection.

#### 2.3 Manual Soldering

- (1) Observe temperature and time soldering specifications or do not exceed temperatures of 400  $^{\circ}$ C for 3 seconds or less.
- (2) If lead wires must be formed to meet terminal board hole spacing, avoid stress on the lead wire where it enters the capacitor seal.
- (3) If a soldered capacitor must be removed and reinserted, avoid excessive stress to the capacitor leads.
- (4) Avoid touching the tip of the soldering iron to the capacitor, to prevent melting of the vinyl sleeve.

#### 2.4 Flow Soldering

- (1) Do not immerse the capacitor body into the solder bath as excessive internal pressure could result.
- (2) Observe proper soldering conditions (temperature, time, etc.) Do not exceed the specified limits.
- (3) Do not allow other parts or components to touch the capacitor during soldering.
- 2.5 Other Soldering Considerations

Rapid temperature rises during the preheat operation and resin bonding operation can cause cracking of the capacitor vinyl sleeve.

For heat curing, do not exceed 150°C for a maximum time of 2 minutes.

- 2.6 Capacitor Handling after Solder
  - (1). Avoid movement of the capacitor after soldering to prevent excessive stress on the lead wires where they enter the seal.
  - (2). Do not use capacitor as a handle when moving the circuit board assembly.

(3). Avoid striking the capacitor after assembly to prevent failure due to excessive shock.

	Version	01		Page	15
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#### 2.7 Circuit Board Cleaning

- \* (1) Circuit boards can be immersed or ultrasonically cleaned using suitable cleaning solvents for up 5 minutes and up to  $60^{\circ}$ C maximum temperatures. The boards should be thoroughly rinsed and dried.
- The use of ozone depleting cleaning agents is not recommended in the interest of protecting the environment.
- \* (2) Avoid using the following solvent groups unless specifically allowed for in the specification;
- Halogenated cleaning solvents: except for solvent resistant capacitor types, halogenated solvents can permeate the seal and cause internal capacitor corrosion and failure. For solvent resistant capacitors, carefully follow the temperature and time requirements of the specification. 1-1-1 trichloroethane should never be used on any aluminum electrolytic capacitor.
- Alkali solvents : could attack and dissolve the aluminum case.
- Petroleum based solvents: deterioration of the rubber seal could result.
- . Xylene : deterioration of the rubber seal could result.
- Acetone : removal of the ink markings on the vinyl sleeve could result.
- \* (3) A thorough drying after cleaning is required to remove residual cleaning solvents which may be trapped between the capacitor and the circuit board. Avoid drying temperatures, which exceed the maximum rated temperature of the capacitor.
- \* (4) Monitor the contamination levels of the cleaning solvents during use by electrical conductivity, pH, specific gravity, or water content. Chlorine levels can rise with contamination and adversely affect the performance of the capacitor.

Please consult us for additional information about acceptable cleaning solvents or cleaning methods.

#### 2.8 Mounting Adhesives and Coating Agents

When using mounting adhesives or coating agents to control humidity, avoid using materials containing halogenated solvents. Also, avoid the use of chloroprene based polymers. After applying adhesives or coatings, dry thoroughly to prevent residual solvents from being trapped between the capacitor and the circuit board.

#### 3. Precautions for using capacitors

#### 3.1 Environmental Conditions

- Capacitors should not be stored or used in the following environments.
- \* (1) Temperature exposure above the maximum rated or below the minimum rated temperature of the capacitor.
- \* (2) Direct contact with water, salt water, or oil.
- \* (3) High humidity conditions where water could condense on the capacitor.
- \* (4) Exposure to toxic gases such as hydrogen sulfide, sulfuric acid, nitric acid chlorine, or ammonia.
- \* (5) Exposure to ozone, radiation, or ultraviolet rays.
- \* (6) Vibration and shock conditions exceeding specified requirements.

**3.2 Electrical Precautions** 

- (1) Avoid touching the terminals of the capacitor as possible electric shock could result. The exposed aluminum case is not insulated and could also cause electric shock if touched.
- (2) Avoid short circuit the area between the capacitor terminals with conductive materials including liquids such as acids or alkaline solutions.

#### 4. Emergency Procedures

- (1) If the pressure relief vent of the capacitor operates, immediately turn off the equipment and disconnect form the power source. This will minimize additional damage caused by the vaporizing electrolyte.
- (2) Avoid contact with the escaping electrolyte gas which can exceed  $100^{\circ}$ C temperatures.

If electrolyte or gas enters the eye, immediately flush the eyes with large amounts of water.

- If electrolyte or gas is ingested by month, gargle with water.
- If electrolyte contacts the skin, wash with soap and water.

Version	01	Page	16

#### 5. Long Term Storage

Leakage current of a capacitor increases with long storage times. The aluminum oxide film deteriorates as a function of temperature and time. If used without reconditioning, an abnormally high current will be required to restore the oxide film. This current surge could cause the circuit or the capacitor to fail. After one year, a capacitor should be reconditioned by applying rated voltage in series with a  $1000\Omega$ , current

limiting resistor for a time period of 30 minutes .

#### 5.1 Environmental Conditions

The capacitor shall be not use in the following condition:

- (1) Temperature exposure above the maximum rated or below the minimum rated temperature of the capacitor.
- (2) Direct contact with water, salt water, or oil.
- (3) High humidity conditions where water could condense on the capacitor.
- (4) Exposure to toxic gases such as hydrogen sulfide, sulfuric acid, nitric acid, chlorine, or ammonia.
- (5) Exposure to ozone, radiation, or ultraviolet rays.
- (6) Vibration and shock conditions exceeding specified requirements.

#### 6. Capacitor Disposal

When disposing of capacitors, use one of the following methods.

- \* Incinerate after crushing the capacitor or puncturing the can wall (to prevent explosion due to internal pressure rise). Capacitors should be incinerated at high temperatures to prevent the release of toxic gases such as chlorine from the polyvinyl chloride sleeve, etc.
- \* Dispose of as solid waste.

NOTE: Local laws may have specific disposal requirements, which must be followed.

Version	01	Page	17